Item	Qty	Reference	Description	Size	Value	MFR
1	1	C20	Capacitor, Ceramic	0603	0.01uF/25V	STD
2	1	C44	Capacitor, Ceramic	0603	0.1uF/50V	STD
3	1	C22	Capacitor, Ceramic	0603	1uF/16V	STD
4	1	C1	Capacitor, Ceramic	0603	3.3nF/50V	STD
5	1	C50	Capacitor, Ceramic	0603	NA	STD
6	2	C2 C4	Capacitor, Ceramic	0805	10uF/6.3V	STD
7	2	C3 C5	Capacitor, Ceramic	0805	NA	STD
8	1	C7	Capacitor, Ceramic	0805	1uF/25V	STD
9	1	C6	Capacitor, Ceramic	0805	2.2uF/16V	STD
10	1	J1	100mil connenctor			STD
11	1	D3	Diode, Schottky, 75V, 0.25A, SOD-323	SOD-323	1N4148WS	STD
12	1	U12	48V, 325mA Wide Vin Synchronous Step-down	WSON-8	LM25018SD/NOPB	TI
			Regulator with Integrated MOSFETs			
13	1	T1	Transformer, MTC-0017SG			MNC
14	2	R69 R3	Resistor, Chip, 1/10W, 1%	0603	10K	STD
15	1	R5	Resistor, Chip, 1/10W, 1%	0603	2.7K	STD
16	1	R34	Resistor, Chip, 1/10W, 1%	0603	15K	STD
17	1	R32	Resistor, Chip, 1/10W, 1%	0603	240K	STD
18	1	R33	Resistor, Chip, 1/10W, 1%	0603	43K	STD
19	3	R4 R1-2	Resistor, Chip, 1/10W, 1%	0603	NA	STD
20	2	D1-2	DIODE SCHOTTKY 40V 0.4A SOD323	SOD-323	ZHCS400	Diodes
21	2	D4 D5	Diode, Zener, 5.6V, 400mW, SOD-323	SOD-323	5.6V	STD

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